EIE Enterprise (M) Sdn. Bhd. (944691-T)

EIE St 639LF
Low solids no-clean flux
(For Tin-Lead and Lead-free alloy wave-soldering)

DESCRIPTION

EIE St 639LF is a low solid, halogen-free no-clean flux that is designed specifically for use in the electronic industry to improve effectiveness in the wave soldering of conventional and SMT circuit boards assemblies. This formula is suitable for lead-free alloys (SnCu and SnAgCu) and leaded SnPb solder. Boards are cosmetically clean when exit soldered-wave and the post-soldering residue is non-conductive, non-corrosive and need not be removed. This formula is designed to yield a better aesthetic cleanliness edge compared to most other no-clean fluxes suitable for lead-free alloys.

APPLICATION

EIE ST 639LF is specifically designed for foam or spray fluxing. It is formulated to solder effectively on HASL (hot air solder leveling) immersion silver or gold substrate material assembly boards. To achieve good solder-yield, it is recommended to preheating the top's component side of the assembly board to (95 – 105) °C prior entry to wave-soldering.

PHYSICAL PROPERTIES

	639LF	Thinner T600
Specific Gravity @25°C	0.833 ± 0.003	0.783 ± 0.003
Acid Number	26.0 ± 2.0	--
Solid Content % (w/w)	3.9	--
Appearance	Clear Straw	Clear
Flash Point (T.O.C.)	18°C	18°C
Copper Mirror Corrosion	Pass	--
Silver Chromate Paper Test	Pass	--
Surface Insulation Resistance (As Per IPC-TM-650)		
Day 4 (96 hrs) ohm	2.3×10^{10}	--
Day 7 (168 hrs) ohm	2.8×10^{10}	--
Minimum passed requirement (7 days)	1.0×10^{8}	--

STORAGE

EIE St 639LF flux is alcohol-based and is flammable. Store in no direct sunlight and keep away from sources of ignition.

PACKING

25 litre/carboy or 200litre HDPE drum

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